

September 2007

FDG6342L

Integrated Load Switch

Features

- Max $r_{DS(on)} = 150 m\Omega$ at $V_{GS} = 4.5 V$, $I_D = -1.5 A$
- Max $r_{DS(on)} = 195m\Omega$ at $V_{GS} = 2.5V$, $I_D = -1.3A$
- Max $r_{DS(on)} = 280m\Omega$ at $V_{GS} = 1.8V$, $I_D = -1.1A$
- Max $r_{DS(on)} = 480 \text{m}\Omega$ at $V_{GS} = 1.5 \text{V}$, $I_D = -0.9 \text{A}$
- Control MOSFET (Q1) includes Zener protection for ESD ruggedness (>4KV Human body model)
- High performance trench technology for extremely low r_{DS(on)}
- Compact industry standard SC70-6 surface mount package
- RoHS Compliant

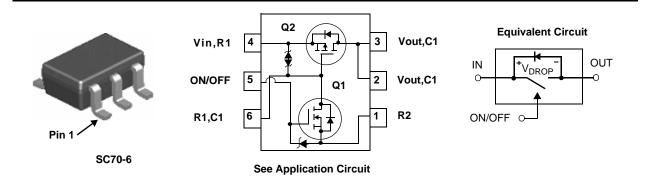


General Description

This device is particularly suited for compact power management in portable electronic equipment where 1.5V to 8V input and 1.5A output current capability are needed. This load switch integrates a small N-Channel power MOSFET (Q1) that drives a large P-Channel power MOSFET (Q2) in one tiny SC70-6 package.

Applications

- Power management
- Load switch



MOSFET Maximum Ratings T_A = 25°C unless otherwise noted

Symbol	Parameter	Ratings	Units		
V _{IN}	Gate to Source Voltage (Q2)		±8	V	
V _{ON/OFF}	Gate to Source Voltage (Q1)		-0.5 to 8	V	
I _{Load}	Load Current -Continuous	(Note 2)	-1.5	Α	
	-Pulsed	(Note 2)	-6		
Б	Power Dissipation for Single Operation	(Note 1a)	0.36	W	
P_{D}		(Note 1b)	0.3	VV	
T _J , T _{STG}	Operating and Storage Junction Temperature Range		-55 to +150	°C	

Thermal Characteristics

$R_{\theta JA}$	Thermal Resistance, Junction to Ambient Single operation	(Note 1a)	350	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient Single operation	(Note 1b)	415	*C/VV

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	n Quantity	
.42	FDG6342L	SC70-6	7"	8mm	3000units	

Electrical Characteristics $T_J = 25^{\circ}\text{C}$ unless otherwise noted Parameter

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Chara	octeristics					
BV_{IN}	V _{IN} Breakdown Voltage	$I_D = -250 \mu A, V_{ON/OFF} = 0 V$	8			V
I _{Load}	Zero Gate Voltage Drain Current	$V_{IN} = -6.4V$, $V_{ON/OFF} = 0V$			-1	μА
I _{FL}	Leakage Current, Forward	$V_{IN} = 8V, V_{ON/OFF} = 0V$			10	μΑ
I _{RL}	Leakage Current, Reverse	$V_{IN} = -8V$, $V_{ON/OFF} = 0V$			-10	μΑ

On Characteristics (note 2)

V _{ON/OFF(th)}	Gate Threshold Voltage	$V_{IN} = V_{ON/OFF}, I_D = -250\mu A$	0.65	0.8	1.5	V
	Static Drain to Source On Resistance (Q2)	$V_{IN} = 4.5V, I_D = -1.5A$		125	150	mΩ
		$V_{IN} = 2.5V, I_D = -1.3A$		150	195	
r _{DS(on)}		$V_{IN} = 1.8V, I_D = -1.1A$		200	280	
		$V_{IN} = 1.5V, I_D = -0.9A$		250	480	
	I Static Drain to Source On Resistance (QT)	$V_{IN} = 4.5V, I_D = 0.4A$		2.6	4.0	Ω
		$V_{IN} = 2.7V, I_D = 0.2A$		3.3	5.0	22

Drain-Source Diode Characteristics

Į	S	Maximum Continuous Drain to Source Diode Forward Current			-0.25	V	
٧	/ _{SD}	Source to Drain Diode Forward Voltage	$V_{ON/OFF} = 0V, I_S = -0.25A \text{ (Note 2)}$		-0.6	-1.2	V

1. $R_{\theta JA}$ is determined with the device mounted on a 1in² pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material. $R_{\theta JC}$ is guaranteed by design while $R_{\theta JA}$ is determined by the user's board design.



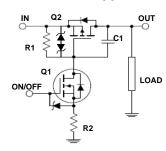
a. 350°C/W when mounted on a 1 in² pad of 2 oz copper.



b. 415°C/W when mounted on a minimum pad of 2 oz copper.

2. Pulse Test: Pulse Width < 300μ s, Duty cycle < 2.0%.

FDG6342LLoad Switch Application circuit



External Component Recommendation:

For additional in-rush current control, R2 and C1 can be added. For more information, see application note AN1030

Typical Characteristics T_J = 25°C unless otherwise noted

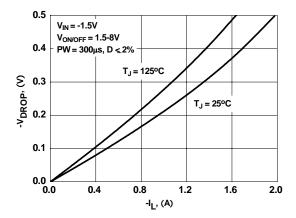


Figure 1. Conduction Voltage Drop Variation with Load Current.

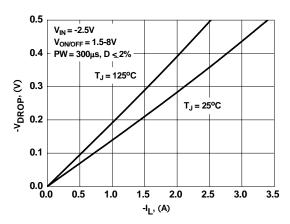


Figure 3. Conduction Voltage Drop Variation with Load Current.

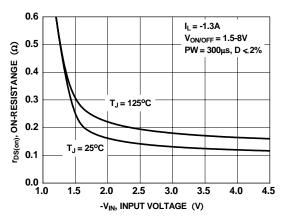


Figure 5. On-Resistance Variation With Input Voltage

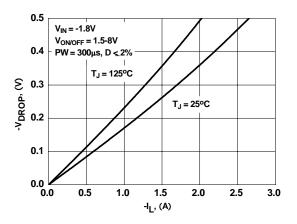


Figure 2. Conduction Voltage Drop Variation with Load Current.

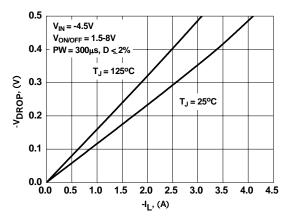


Figure 4. Conduction Voltage Drop Variation with Load Current.

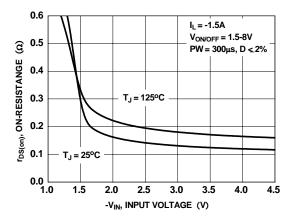
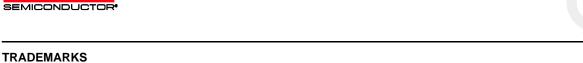


Figure 6. On-Resistance Variation With Input Voltage





The following are registered and unregistered trademarks and service marks Fairchild Semiconductor owns or is authorized to use and is not intended to be an exhaustive list of all such trademarks.

Green FPS™ ACFx® Power247® SuperSOT™-8 POWEREDGE® Build it Now™ Green FPS™ e-Series™ SvncFET™ The Power Franchise® CorePLUS™ GTO™ Power-SPM™ PowerTrench® CROSSVOLT™ i-Lo™ Jwer' CTL™ IntelliMAX™ Programmable Active Droop™ ISOPLANAR™ **OFFT®** TinyBoost™ Current Transfer Logic™ EcoSPARK® MegaBuck™ QSTM TinyBuck™ TinyLogic[®] MICROCOUPLER™ QT Optoelectronics™ $\vec{\text{F}}\text{airchild}^{\text{@}}$ TINYOPTO™ MicroFET™ Quiet Series™ Fairchild Semiconductor® MicroPak™ RapidConfigure™ TinyPower™ TinyPWM™ FACT Quiet Series™ MillerDrive™ SMART START™ **FACT®** Motion-SPM™ SPM[®] TinyWire™ $\mathsf{FAST}^{\mathbb{R}}$ OPTOLOGIC® STEALTH™ µSerDes™ OPTOPLANAR® UHC® FastvCore™ SuperFET™ FPS™ UniFET™ SuperSOT™-3 FRFET® PDP-SPM™ SuperSOT™-6 VCX™ Power220® Global Power ResourceSM

DISCLAIMER

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION, OR DESIGN. FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS. THESE SPECIFICATIONS DO NOT EXPAND THE TERMS OF FAIRCHILD'S WORLDWIDE TERMS AND CONDITIONS, SPECIFICALLY THE WARRANTY THEREIN, WHICH COVERS THESE PRODUCTS.

LIFE SUPPORT POLICY

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF FAIRCHILD SEMICONDUCTOR CORPORATION.

- Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury to the user.
- 2. A critical component in any component of a life support, device, or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

PRODUCT STATUS DEFINITIONS

Definition of Terms

Datasheet Identification	Product Status	Definition
Advance Information	Formative or In Design	This datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	This datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
Obsolete	Not In Production	This datasheet contains specifications on a product that has been discontinued by Fairchild Semiconductor. The datasheet is printed for reference information only.

Rev I31